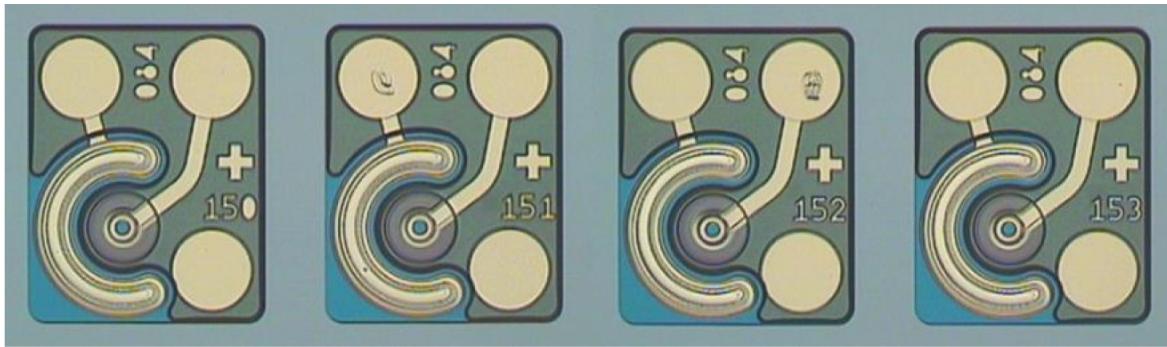


# 850 nm 25 Gbps DUAL TOP CONTACT MULTIMODE VCSEL ARRAY

**APA4501010001**

**APA4501040001**

**APA4501120001**



## FEATURES

- 850 nm multimode emission
- Data rates from DC to 25 Gb/s
- Dual top contact configuration with common cathode electrodes
- High reliability
- High humidity robustness, NemoTM technology, GR468
- RoHS compliant
- Available as single chip, 4 and 12 channel array
- RoHS compliant 

## APPLICATIONS

- Single channel and parallel fiber optical communication links
- Transceivers, active optical cables

## SHIPMENT PACKAGING OPTIONS

- Diced wafer on UV tape on metal lead frame
- Grip ring
- Gel-Pak

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## Electro-Optical Characteristics

T = 25 °C unless otherwise noted

Parameter	Symbol	Conditions	Ratings			Unit
			Min	Typ	Max	
Threshold current	$I_{th}$	T = 25 °C		0.7	0.9	mA
		T = 0 °C - 80 °C			1.2	
Slope efficiency	$\eta$	$\eta = I_{th} + 1 \text{ mA}, T = 25 \text{ °C}$	0.3	0.45		mW/mA
		$\eta = I_{th} + 1 \text{ mA}, T = 80 \text{ °C}$	0.25	0.35		
Optical output power	$P_{out}$	$I_{op} = 6.0 \text{ mA}, T = 25 \text{ °C}$	1.8	2.2		mW
		$I_{op} = 7.0 \text{ mA}, T = 80 \text{ °C}$	1.5			
Operating voltage	$U_{op}$	$I_{op} = 6 \text{ mA}$		2.1	2.2	V
Differential resistance	$R_d$	$I_{op} = 6 \text{ mA}, T = 0 \text{ °C} - 85 \text{ °C}$		80	90	Ω
Emission wavelength	$\lambda$	$I_{op} = 6.0 \text{ mA}, T = 0 \text{ °C} - 80 \text{ °C}$	840	850	860	nm
Spectral width, RMS	$\Delta\lambda$	$I_{op} = 6 \text{ mA}$			0.65	nm
Modulation bandwidth	$f_{3dB}$	$I_{op} = 6 \text{ mA}, T = 25 \text{ °C}$	13	14.5		GHz
		$I_{op} = 7 \text{ mA}, T = 80 \text{ °C}$	12.5	13.5		
Beam divergence	$\Theta$	$I_{op} = 6.0 \text{ mA}, \text{ Full width } 1/e^2$		28	33	°
Relative intensity noise	$RIN_{(OMA)}$	$I_{op} = 7.0 \text{ mA}, ER = 4 \text{ dB, } 19 \text{ GHz BW}$		-130	-128	dB/Hz
Threshold uniformity	$\Delta I_{th}$	Range across 1x4 and 1x12 array chips			0.15	mA
Slope efficiency uniformity	$\Delta\eta$				0.05	mW/mA

## Thermal Characteristics

Parameter	Symbol	Conditions	Ratings			Unit
			Min	Typ	Max	
Wavelength tuning coefficient 0 °C - 80 °C	$\delta\lambda/\delta T$			0.06		nm/K
Slope efficiency variation 0 °C - 80 °C	$\Delta\eta T$			-0.35		%/K
Thermal impedance	$Z_{th}$			3.0		K/mW

## Absolute Maximum Ratings

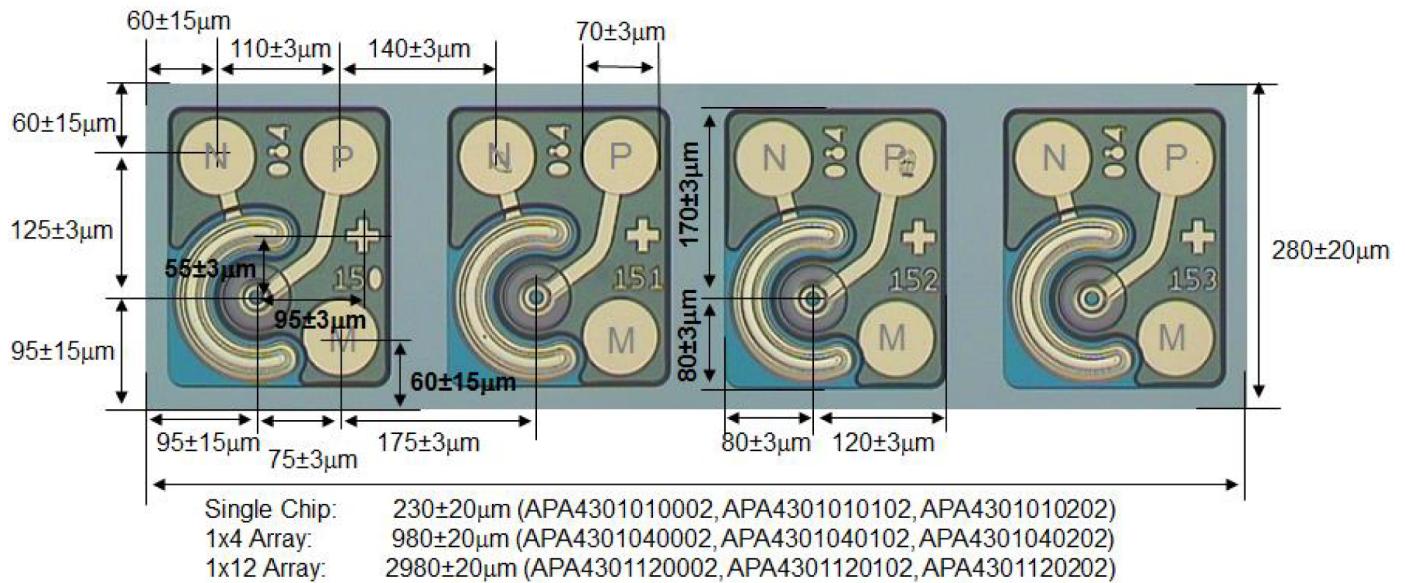
Parameter	Rating	Unit
Optical output power	8	mW
Peak forward current (max. 10sec)	12	mA
VCSEL reverse voltage	5	V
Operating temperature	0 to +80	°C
Storage temperature	-40 to +100	°C
Mounting temperature (max. 10sec)	260	°C

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## Chip Outer Dimensions

Parameter		Min	Typ	Max	Unit
Die length, APA4501010001, APA4501010101, APA4501010201		210	230	250	μm
Die length, APA4501040001, APA4501040101, APA4501040201		960	980	1000	μm
Die length, APA4501120001, APA4501120101, APA4501120201		2960	2980	3000	μm
Die width		260	280	300	μm
Die height		135	150	165	μm

## Chip Layout



N: n-contact (common cathode)

P: p-contact (anode)

M: mechanical pad

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## RoHS Compliance

Coherent is fully committed to environment protection and sustainable development and has set in place a comprehensive program for removing polluting and hazardous substances from all of its products. The relevant evidence of RoHS compliance is held as part of our controlled documentation for each of our compliant products. RoHS compliance parts are available to order, please refer to the ordering information section for further details.

## Ordering Information

Product Code	Data Rate	Description	Shipment Packaging
APA4501010001	25 Gb/s	850 nm 25 G MM DTC VCSEL chip	Diced wafer on metal lead frame <sup>(1)</sup>
APA4501040001	25 Gb/s	850 nm 25 G MM 1x4 DTC VCSEL array	Diced wafer on metal lead frame <sup>(1)</sup>
APA4501120001	25 Gb/s	850 nm 25 G MM 1x12 DTC VCSEL array	Diced wafer on metal lead frame <sup>(1)</sup>
APA4501010101	25 Gb/s	850 nm 25 G MM DTC VCSEL chip	Grip ring <sup>(2)</sup>
APA4501040101	25 Gb/s	850 nm 25 G MM 1x4 DTC VCSEL array	Grip ring <sup>(2)</sup>
APA4501120101	25 Gb/s	850 nm 25 G MM 1x12 DTC VCSEL array	Grip ring <sup>(2)</sup>
APA4501010201	25 Gb/s	850 nm 25 G MM DTC VCSEL chip	Gel-Pak <sup>(3)</sup>
APA4501040201	25 Gb/s	850 nm 25 G MM 1x4 DTC VCSEL array	Gel-Pak <sup>(3)</sup>
APA4501120201	25 Gb/s	850 nm 25 G MM 1x12 DTC VCSEL array	Gel-Pak <sup>(3)</sup>

<sup>(1)</sup> Full diced 3" wafer on UV tape on metal lead frame Ø 230 mm, electronic wafermap provided (standard high volume)

<sup>(2)</sup> Known Good Dies on UV tape on grip ring Ø 150 mm (medium volume)

<sup>(3)</sup> Known Good Dies in 2" Gel-Pak (low volume)

## Important Notice

Performance figures, data and any illustrative material provided in this data sheet are typical and must be specifically confirmed in writing by Coherent before they become applicable to any particular order or contract. In accordance with the Coherent policy of continuous improvement specifications may change without notice. Further details are available from any Coherent sales representative.

## Safety Labels



Caution - use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure.